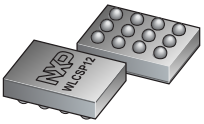


SOT2063-1

WLCSP12, wafer level chip scale package, 12 terminals, 0.35 mm pitch, 1.55 mm x 1.18 mm x 0.455 mm body (backside coating included)

15 April 2021 **Package information**

1 Package summary

Terminal position code	B (bottom)
Package type descriptive code	WLCSP12
Package style descriptive code	WLCSP (wafer level chip-size package)
Mounting method type	S (surface mount)
Issue date	11-03-2021
Manufacturer package code	98ASA01624D

Table 1. Package summary

Parameter	Min	Nom	Max	Unit
package length	1.52	1.55	1.58	mm
package width	1.15	1.18	1.21	mm
seated height	-	0.455	0.485	mm
nominal pitch	-	0.35	-	mm
actual quantity of termination	-	12	-	

WLCSP12, wafer level chip scale package, 12 terminals, 0.35 mm pitch, 1.55 mm x 1.18 mm x 0.455 mm body (backside coating included)

2 Package outline

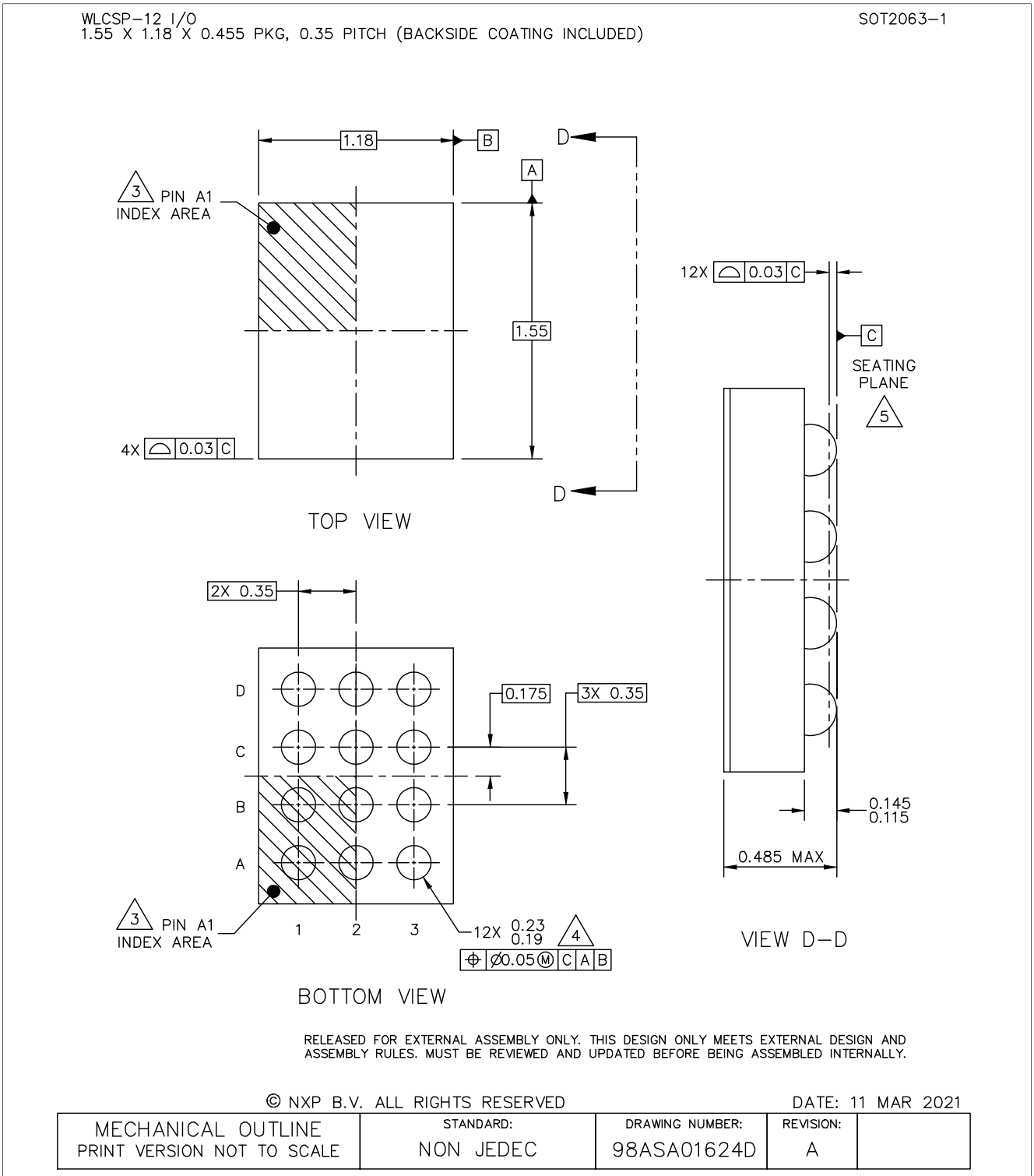


Figure 1. Package outline WLCSP12 (SOT2063-1)

3 Soldering

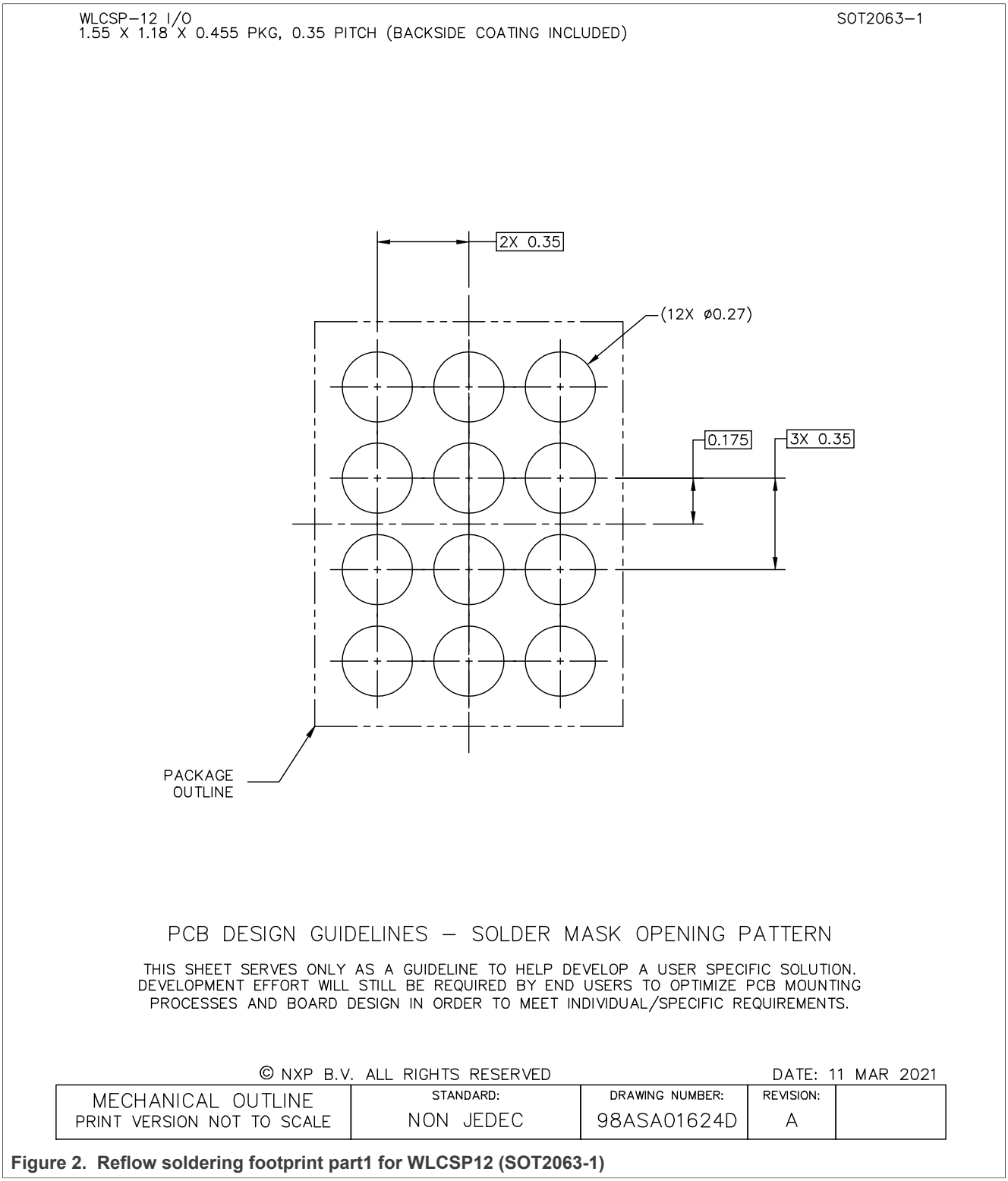
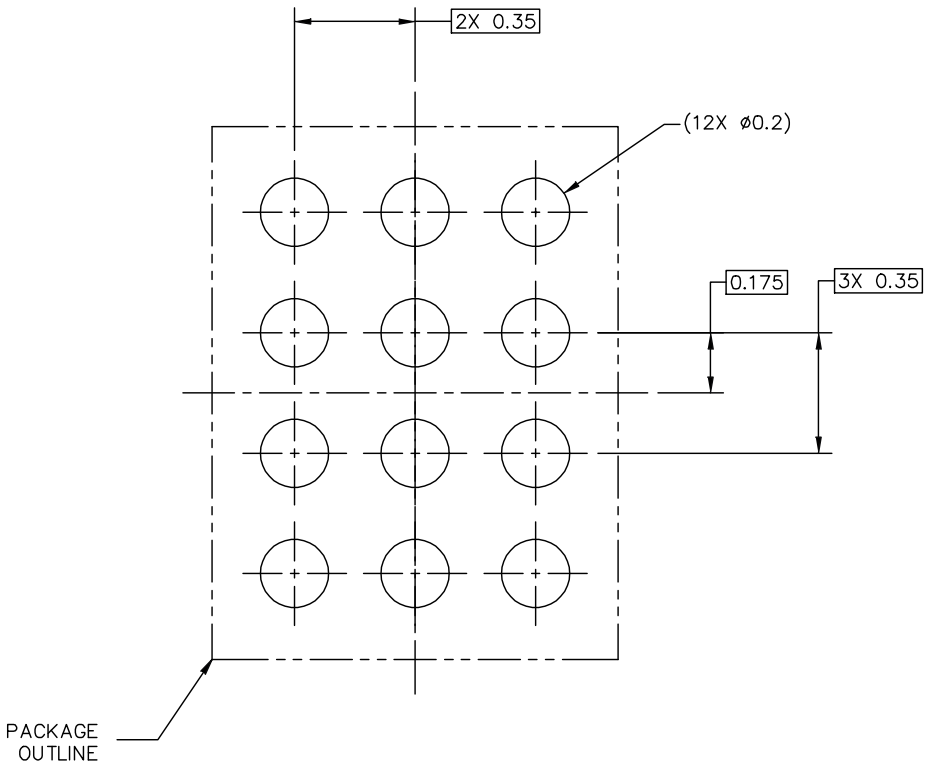


Figure 2. Reflow soldering footprint part1 for WLCSP12 (SOT2063-1)

WLCSP−12 I/O
1.55 X 1.18 X 0.455 PKG, 0.35 PITCH (BACKSIDE COATING INCLUDED)

SOT2063−1



PCB DESIGN GUIDELINES − I/O PADS AND SOLDERABLE AREA

THIS SHEET SERVES ONLY AS A GUIDELINE TO HELP DEVELOP A USER SPECIFIC SOLUTION. DEVELOPMENT EFFORT WILL STILL BE REQUIRED BY END USERS TO OPTIMIZE PCB MOUNTING PROCESSES AND BOARD DESIGN IN ORDER TO MEET INDIVIDUAL/SPECIFIC REQUIREMENTS.

DATE: 11 MAR 2021

MECHANICAL OUTLINE PRINT VERSION NOT TO SCALE	STANDARD: NON JEDEC	DRAWING NUMBER: 98ASA01624D	REVISION: A	

Figure 3. Reflow soldering footprint part2 for WLCSP12 (SOT2063-1)

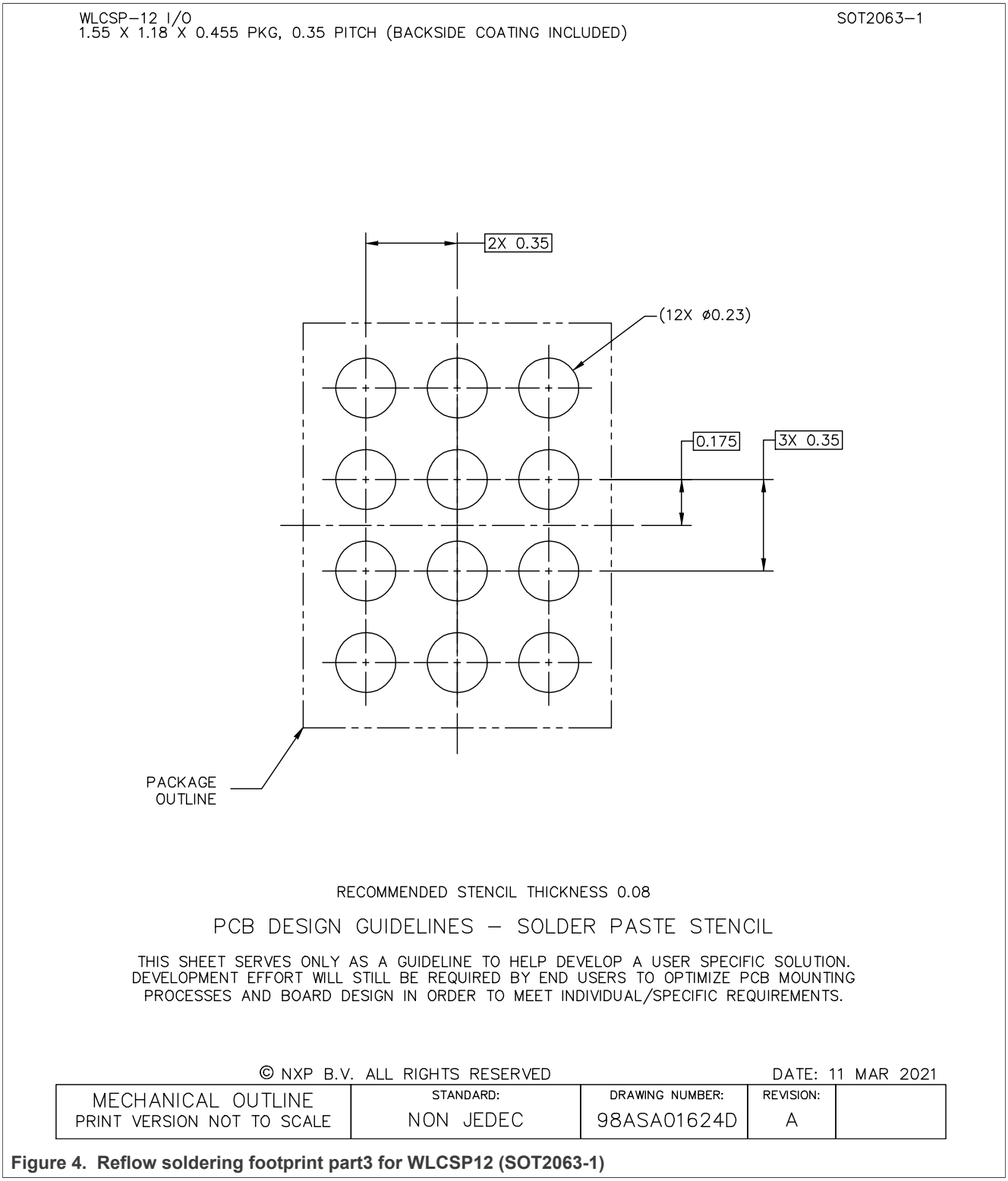


Figure 4. Reflow soldering footprint part3 for WLCSP12 (SOT2063-1)

WLCSP12, wafer level chip scale package, 12 terminals, 0.35 mm pitch, 1.55 mm x 1.18 mm x 0.455 mm body (backside coating included)

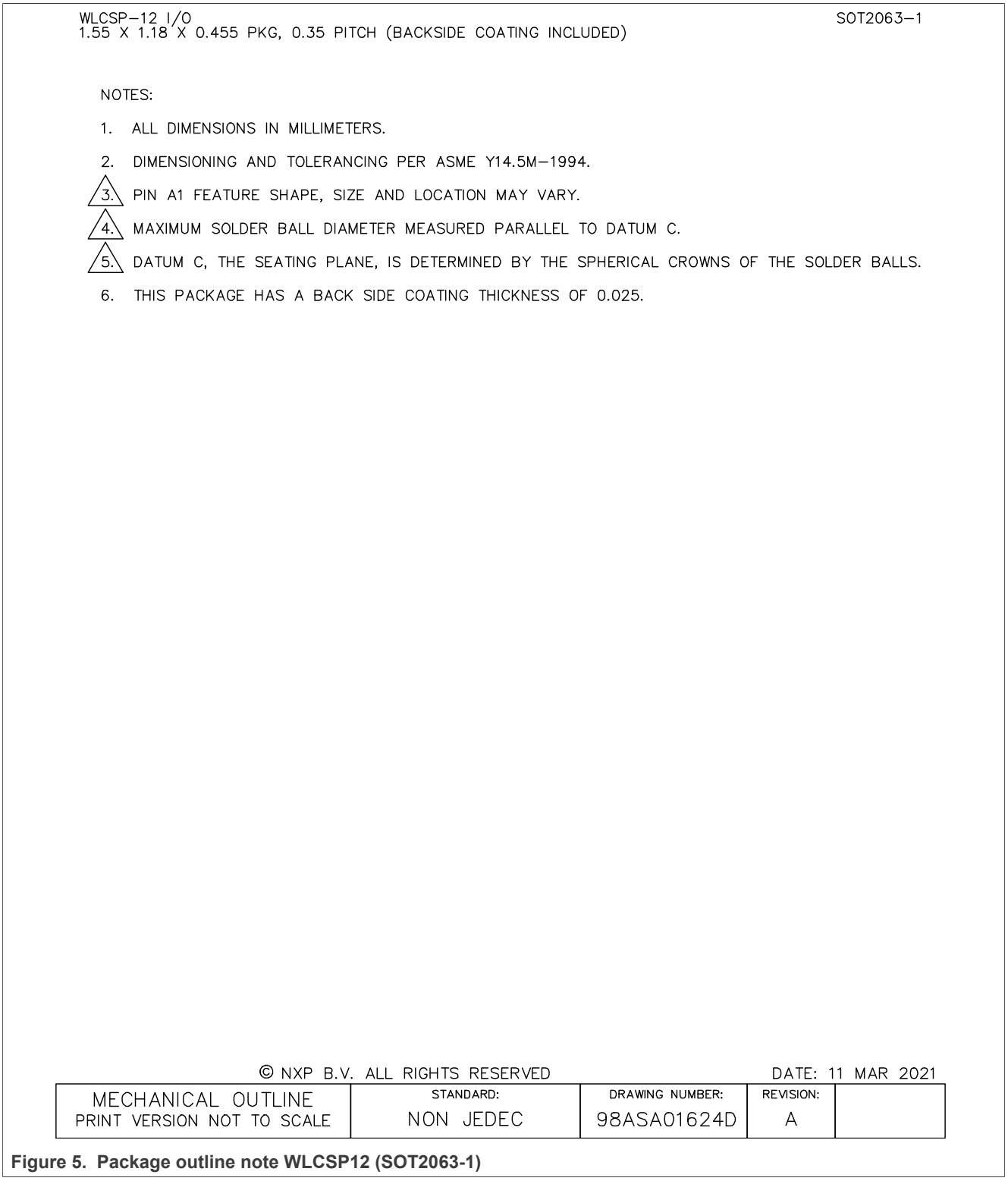


Figure 5. Package outline note WLCSP12 (SOT2063-1)

4 Legal information

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SOT2063-1

WLCSP12, wafer level chip scale package, 12 terminals, 0.35 mm pitch, 1.55 mm x 1.18 mm x 0.455 mm body (backside coating included)

Contents

For more information, please visit: http://www.nxp.com
For sales office addresses, please send an email to: salesaddresses@nxp.com

Date of release: 15 April 2021